











### **Description**

Intexys offers a surface mount Multi Chip Module (MCM) solution for 850nm data communications from 4 to 10Gbit/s. The quasi-hermetic packaged sub-assembly integrates laser (Photodiode), driver (TIA), passive components. The MCM technology used by Intexys results in drastic improvements in circuit density, size, power consumption and cost reduction, and solves signal integrity management problems.

#### **Features**

- Data rate up tp 10Gbit/s
- Unique high density packaging designed for small form factor applications
- Packaged with driver and TIA electronic and related passive components
- Full flip chip assembly internally matched
- Surface mount package
- Low cost effective solution

## **Applications**

- Free Space Optics
- On-Board optical interconnections
- Mobile Applications

#### **Main Transmitter Characteristics**

Min	Тур	Max	Unit
	10,3125	10,7	Gbit/s
-100		100	ppm
	40		ps
	40	50	ps
4	5		dB
	3,75		ps
	30	35	ps
5	10		%
140		160	mW
	-100 4 5	10,3125 -100 40 40 4 5 3,75 30 5 10	10,3125 10,7 -100 100 40 40 50 4 5 3,75 30 35 5 10

#### **Main Receiver Characteristics**

Parameters		Min	Тур	Max	Unit
Data rate				10,7	GBd
Conversion gain $(\lambda = 850 \text{ nm}, -12d\text{Bm})$		10	20	40	mV/μW
Optical sensitivity	850 nm			-12	dBm
	1310 nm			-19	dBm
Output Impedance		42	50	58	Ω
Optical overload (NRZ PRBS 2 <sup>23-1</sup> / BER 10 <sup>-10</sup> )			0		dBm





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